

*ABSTRACT OF THE DISCLOSURE*~~Abstract~~~~Integrated Circuit Arrangement and Method for the Manufacture Thereof~~

A doped region (3) is provided in a substrate (1). A plane ~~with~~ <sup>having</sup> conductive useful structures (71) and a conductive filler structure (72) is arranged at the surface of the substrate (1). The conductive filler structure (72) is conductively connected to the doped region (10, 3). In this way, a charging of the conductive filler structure (72), which is provided for improving the planarity of the circuit arrangement and has no circuit-oriented function, is avoided.

~~Figure 6~~